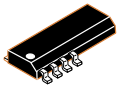
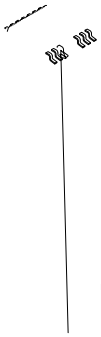
Dual 1-of-4 Decoder/Demultiplexer

MC74AC139, MC74ACT139

MARKING DIAGRAMS



SOIC−16
D SUFFIX
CASE 751B



TSSOP−16
DT SUFFIX
CASE 948F

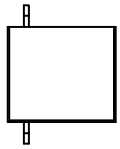


Figure 1. Pinout: 16−Lead Packages Conductors (Top View)

SSIGNMENT

ORDERING INFORMATION

PIN	FUNCTION
—	
— —	

TRUTH TABLE

Inputs			Outputs			
—			—	—	—	—

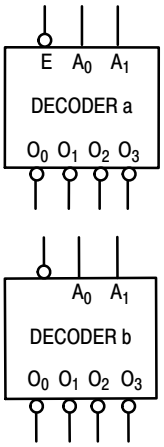
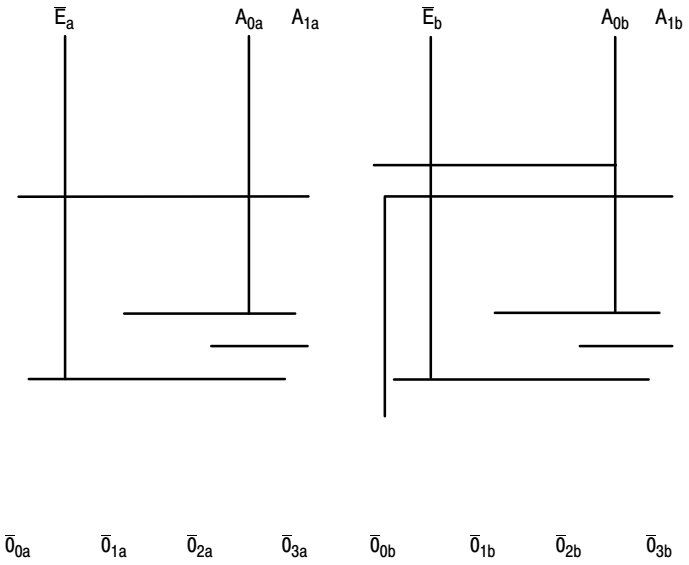


Figure 2. Logic Symbol



MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
		−	
		− ≤ ≤ +	
		− ≤ ≤ +	
		±	

ORDERING INFORMATION

Device Order Number	Marking	Package	Shipping
		– –	
		– –	
		– –	
		– –	
		– –	
–		– –	
		– –	

SOIC−16 9.90x3.90x1.37 1.27P
CASE 751B
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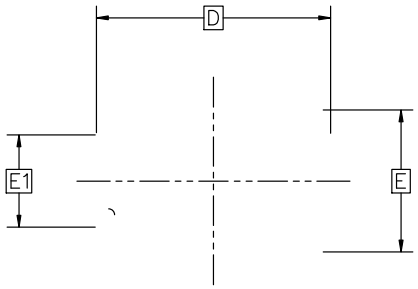
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.1[illegible]

nm TOTAL IN EXCESS OF THE

b DIMENSION AT MAXIMUM MATE



TOP VIEW

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ISSUE M

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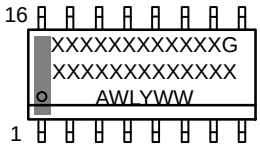
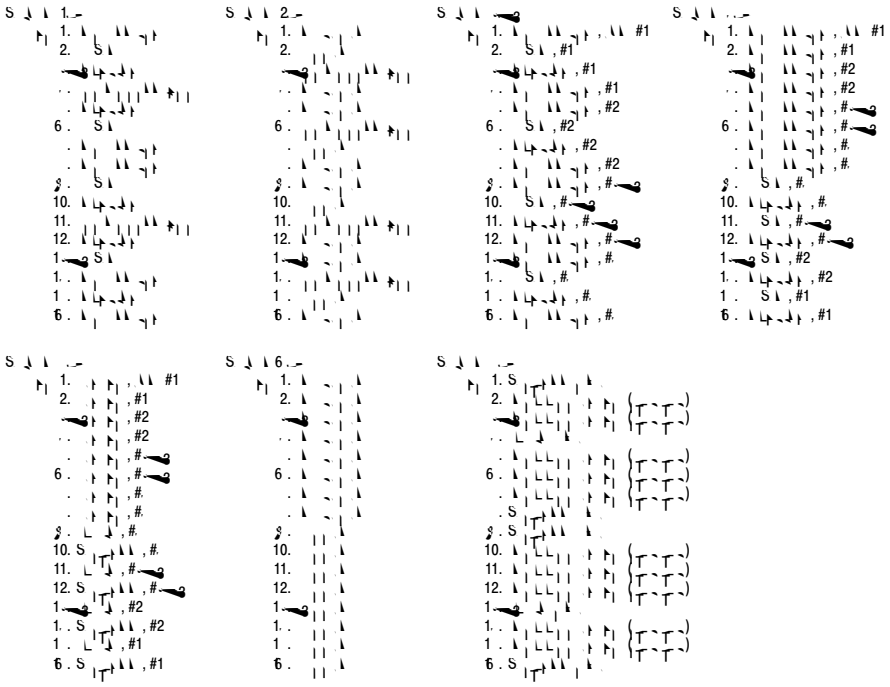
GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.



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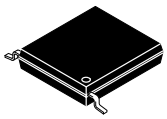
DESCRIPTION:	**SOIC−16 9.90X3.90X1.37 1.27P**		**PAGE 2 OF 2**



SCALE 2:1

TSSOP−16 WB
CASE 948F
ISSUE B

DATE 19 OCT 2006